

BRCM24C16SC SOP-8 16 Kbit I²C

1.7V 2.5~5.5V 1Mhz 1.7~2.5V

400Khz

CMOS 400uA 1.6mA

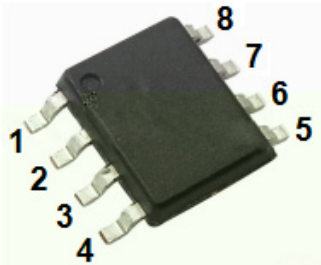
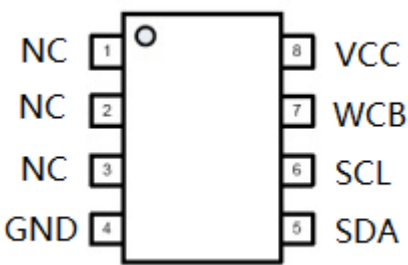
16

128

5ms

100 100 ESD HBM 6KV

+/-200mA;





			mA
			V



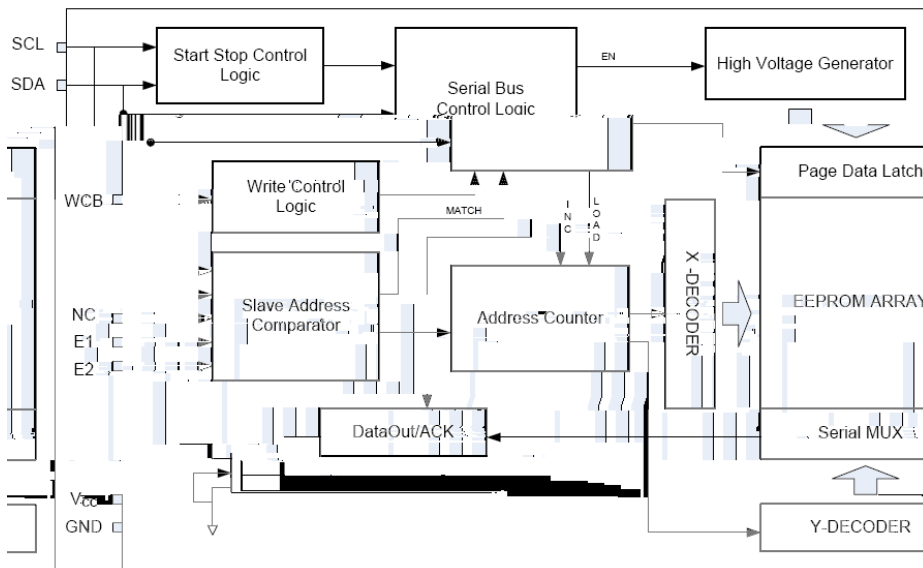
		Ň				

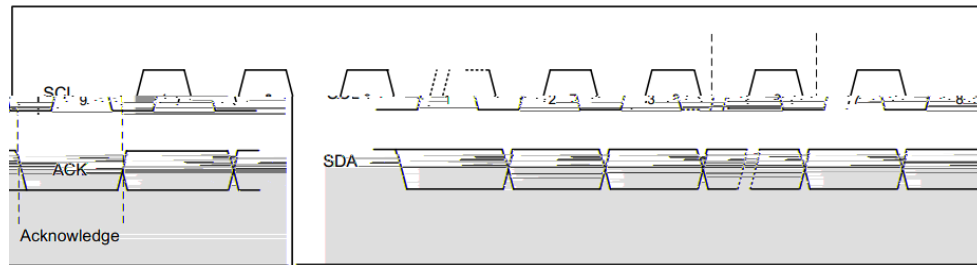
[illegible][illegible]

— °

		≤			≤			

≤





8 / 0 0 1

0

H

BRCM24C16SCWCBVcc

H

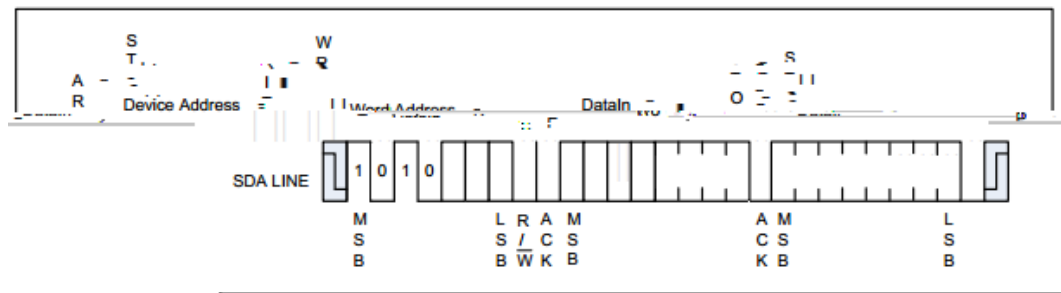
8

BRCM24C16SC“ 0 ”88

BRCM24C16SC“ 0 ”

BRCM24C16SCBRCM24C16SC

(5)

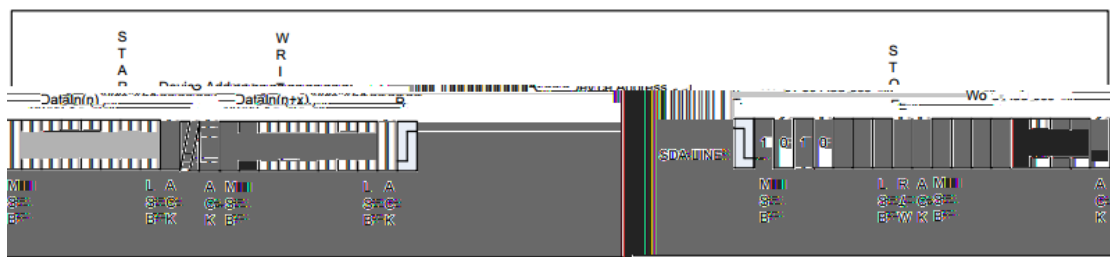


H

BRCM24C16SC

“ 0 ”

BRCM24C16SC



BRCM24C16SC

H

BRCM24C16SC

/

BRCM24C16SC

“ 0 ”

H

16

(a) 1011b

(b) A5 / A4 0 1 A7 / A6 “ 00 ”

(c) A3 / A0

NoACK

H

ID

Lock ID

(a) 1011b;

(b) A6 1 ;

(c) xxxx xx1x x 0 1

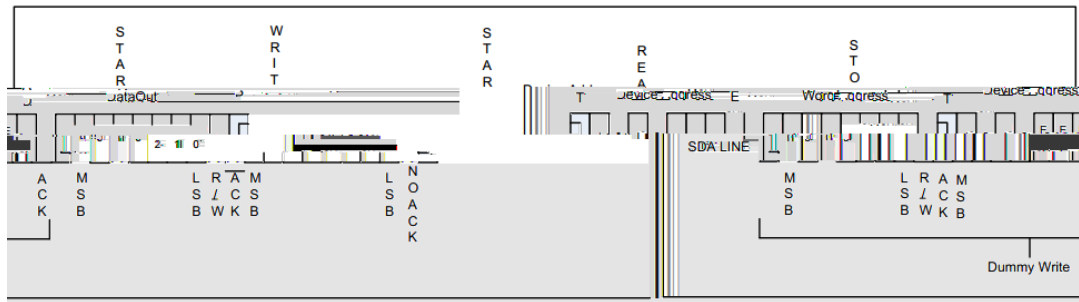
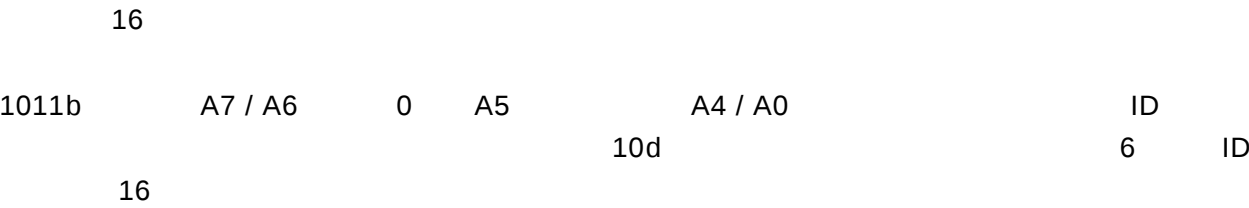


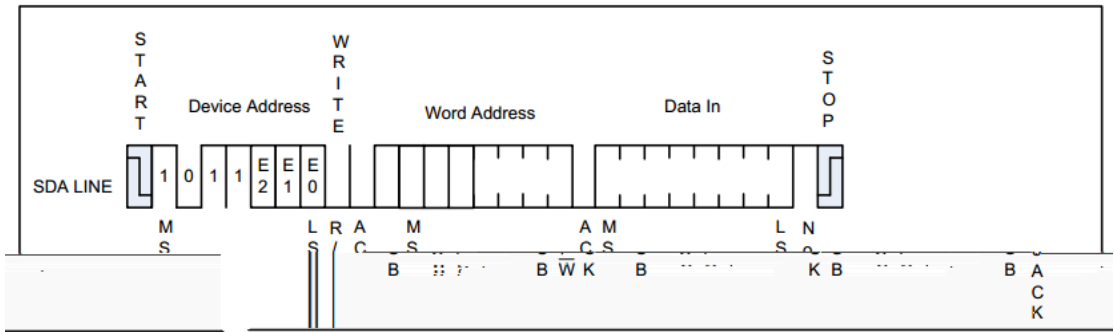
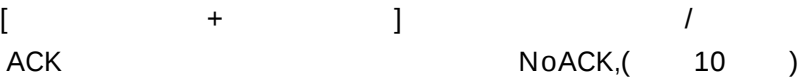
Figure 8 Random Address Read

H

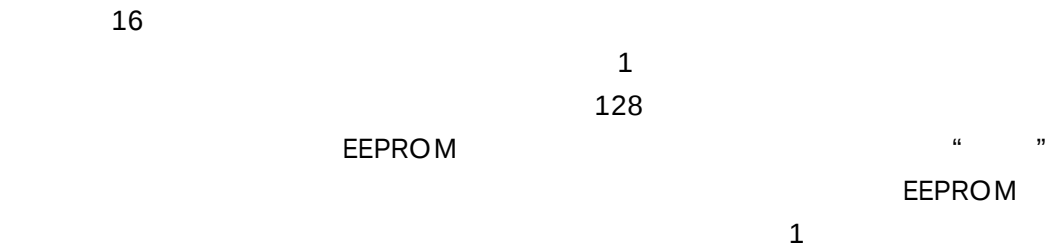
H



H



H



A7 A6 " 10 " 2 " 10 "
 80h
 128 16
 128 ACK
 7

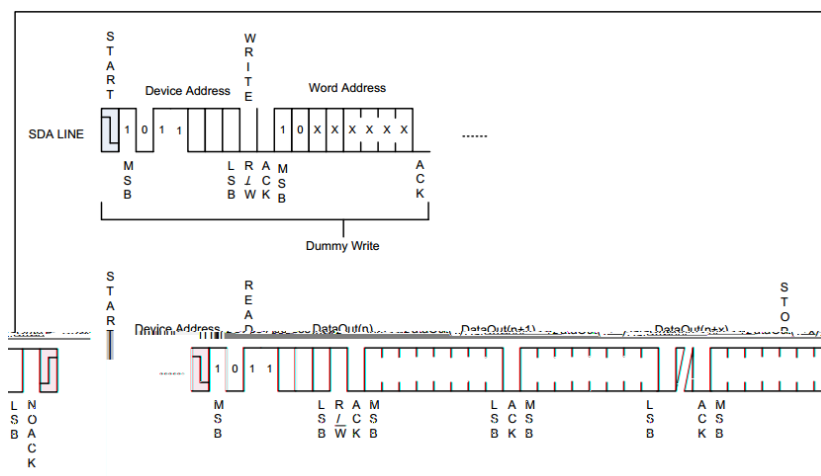
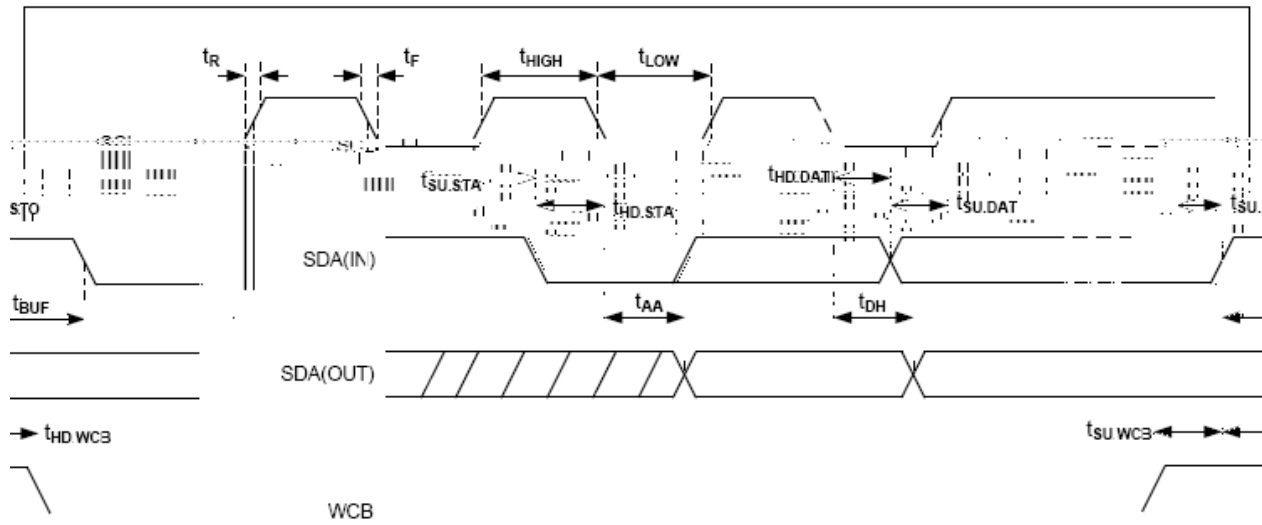
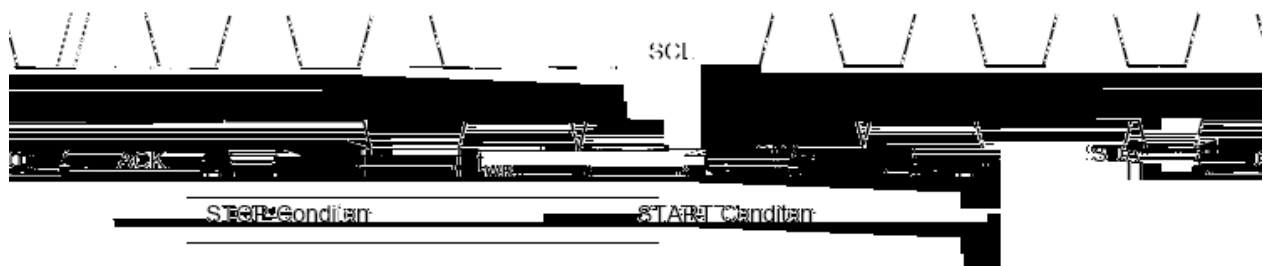


Figure 11 Sequential Read

Bus Timing



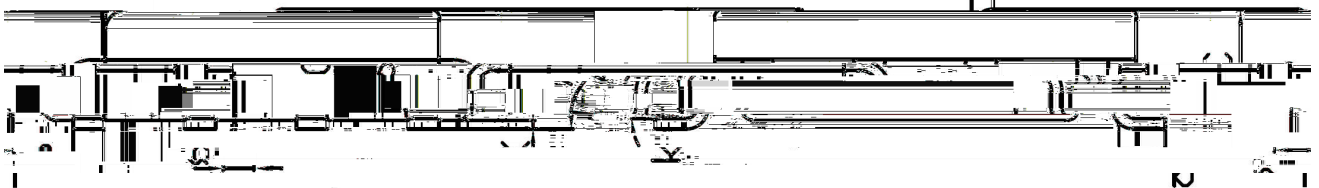
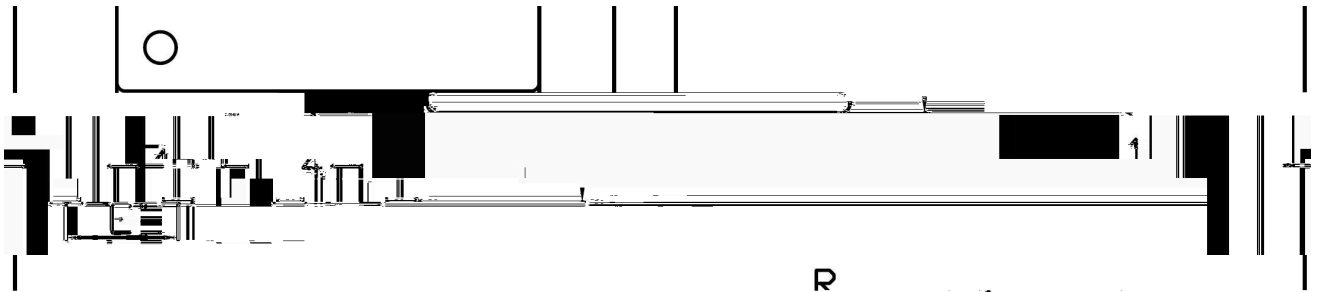
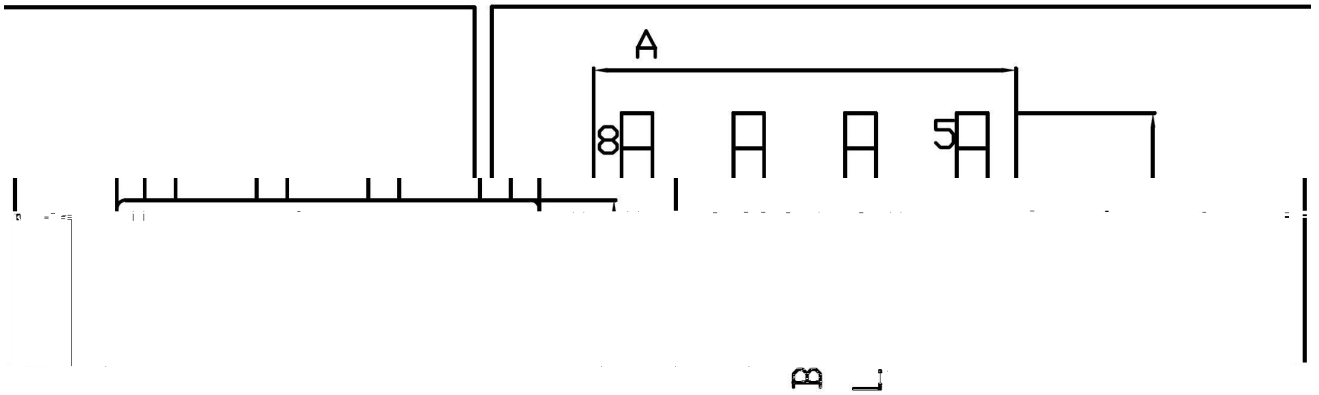
Write Cycle Timing



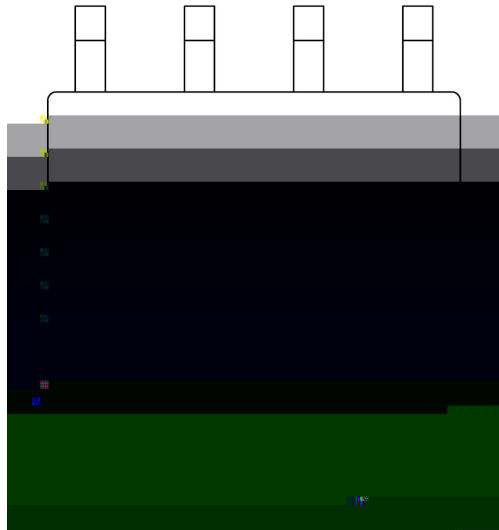
no t_{WDR} is the time from a valid stop condition of a write sequence to the end of the internal clear/write cycle. Note: The write cycle in

单位: mm

11614mm

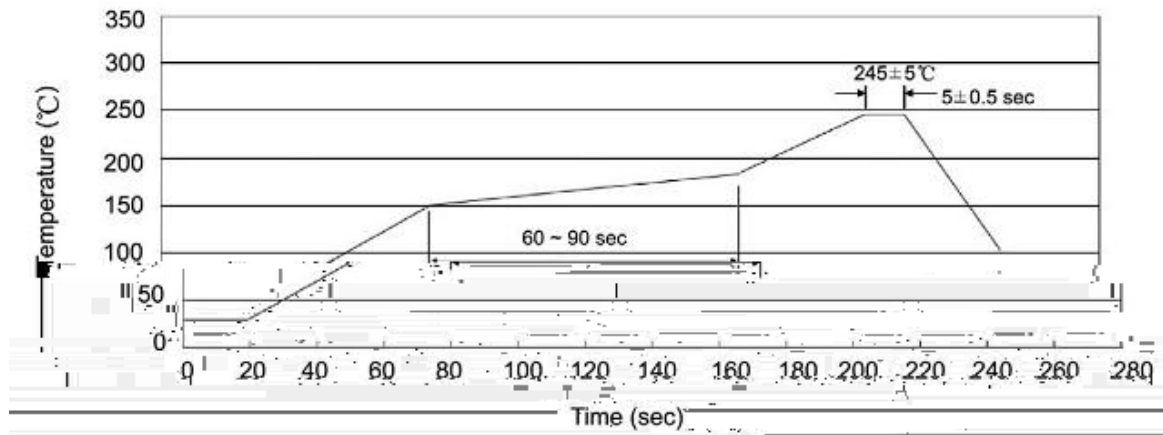


Dimensions in mm (mm)				Dimensions in mm (mm)			
5.40	1.25	1.25	4.70	5.40	1.25	1.25	4.70
0.80	0.80	0.80	0.80	0.80	0.80	0.80	0.80
1.27BSC	P	0°	7°	1.27BSC	P	0°	7°



24C16

Temperature Profile for IR Reflow Soldering(Pb-Free)



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±

±

±

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